## **DISCRETE SEMICONDUCTORS**

# DATA SHEET

# **PDTA143E series** PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

Product data sheet Supersedes data of 2003 Sep 08 2004 Aug 04



## PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

### PDTA143E series

#### **FEATURES**

- Built-in bias resistors
- · Simplified circuit design
- Reduction of component count
- · Reduced pick and place costs.

#### **APPLICATIONS**

- General purpose switching and amplification
- · Inverter and interface circuits
- Circuit driver.

#### QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
$V_{CEO}$	collector-emitter voltage	_	-50	V
Io	output current (DC)	_	-100	mA
R1	bias resistor	4.7	_	kΩ
R2	bias resistor	4.7	_	kΩ

#### **DESCRIPTION**

PNP resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

#### **PRODUCT OVERVIEW**

TVDE NUMBER	PAC	KAGE	MARKING CODE	NDN COMPLEMENT	
TYPE NUMBER	PHILIPS	EIAJ WARKING COL		NPN COMPLEMENT	
PDTA143EE	SOT416	SC-75	01	PDTC143EE	
PDTA143EEF	SOT490	SC-89	50	PDTC143EEF	
PDTA143EK	SOT346	SC-59	01	PDTC143EK	
PDTA143EM	SOT883	SC-101	DL	PDTC143EM	
PDTA143ES	SOT54 (TO-92)	SC-43	TA143E	PDTC143ES	
PDTA143ET	SOT23	_	*01 <sup>(1)</sup>	PDTC143ET	
PDTA143EU	SOT323	SC-70	*01 <sup>(1)</sup>	PDTC143EU	

### Note

<sup>1. \* =</sup> p: Made in Hong Kong.

<sup>\* =</sup> t: Made in Malaysia.

<sup>\* =</sup> W: Made in China.

# PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTA143E series

## SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TVDE NUMBER	CIMPLIFIED OUTLINE AND CYMPOL		PINNING		
TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PIN	DESCRIPTION		
PDTA143ES	1 R1 R2 3 MAM338	1 2 3	base collector emitter		
PDTA143EE PDTA143EEF PDTA143EK PDTA143ET PDTA143EU	3 1 R1 1 R2 1 DD 2 Top view	1 2 3	base emitter collector		
PDTA143EM	2 R1 3 Bottom view  ADB267	1 2 3	base emitter collector		

## PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTA143E series

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-50	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	-50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	-10	V
VI	input voltage				
	positive		_	+10	V
	negative		_	-30	V
Io	output current (DC)		_	-100	mA
I <sub>CM</sub>	peak collector current		_	-100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C			
	SOT23	note 1	_	250	mW
	SOT54	note 1	_	500	mW
	SOT323	note 1	_	200	mW
	SOT346	note 1	_	250	mW
	SOT416	note 1	_	150	mW
	SOT490	notes 1 and 2	_	250	mW
	SOT883	notes 2 and 3	_	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### **Notes**

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60  $\mu$ m copper strip line.

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	in free air		
	SOT23	note 1	500	K/W
	SOT54	note 1	250	K/W
	SOT323	note 1	625	K/W
	SOT346	note 1	500	K/W
	SOT416	note 1	833	K/W
	SOT490	notes 1 and 2	500	K/W
	SOT883	notes 2 and 3	500	K/W

#### **Notes**

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60  $\mu$ m copper strip line.

# PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTA143E series

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0$	_	_	-100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; I_B = 0$	_	_	-1	μΑ
		$V_{CE} = -30 \text{ V}; I_B = 0; T_j = 150 ^{\circ}\text{C}$	-	_	-50	μΑ
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; I_C = 0$	_	_	-0.9	mA
h <sub>FE</sub>	DC current gain	$V_{CE} = -5 \text{ V}; I_{C} = -10 \text{ mA}$	30	_	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = -10 \text{ mA}; I_B = -0.5 \text{ mA}$	-	_	-150	mV
$V_{i(off)}$	input-off voltage	$I_C = -100 \mu A; V_{CE} = -5 V$		-1.1	-0.5	V
$V_{i(on)}$	input-on voltage	$I_C = -20 \text{ mA}; V_{CE} = -0.3 \text{ V}$	-2.5	-1.9	_	V
R1	input resistor		3.3	4.7	6.1	kΩ
<u>R2</u> R1	resistor ratio		0.8	1	1.2	
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0$ ; $V_{CB} = -10 \text{ V}$ ; $f = 1 \text{ MHz}$	_	_	3	pF

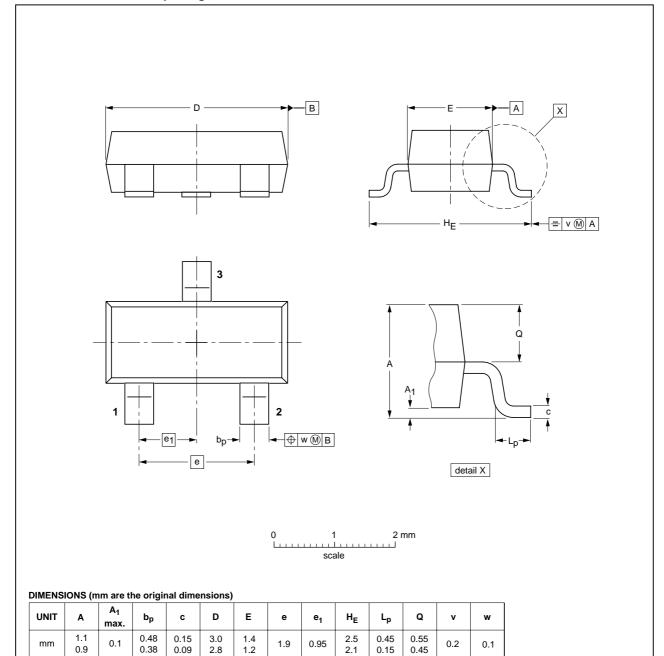
# PNP resistor-equipped transistors; $R1 = 4.7 \text{ k}\Omega$ , $R2 = 4.7 \text{ k}\Omega$

## PDTA143E series

#### **PACKAGE OUTLINES**

Plastic surface-mounted package; 3 leads

SOT23



OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	DEC JEITA		PROJECTION	ISSUE DATE	
SOT23		TO-236AB				<del>-04-11-04-</del> 06-03-16	

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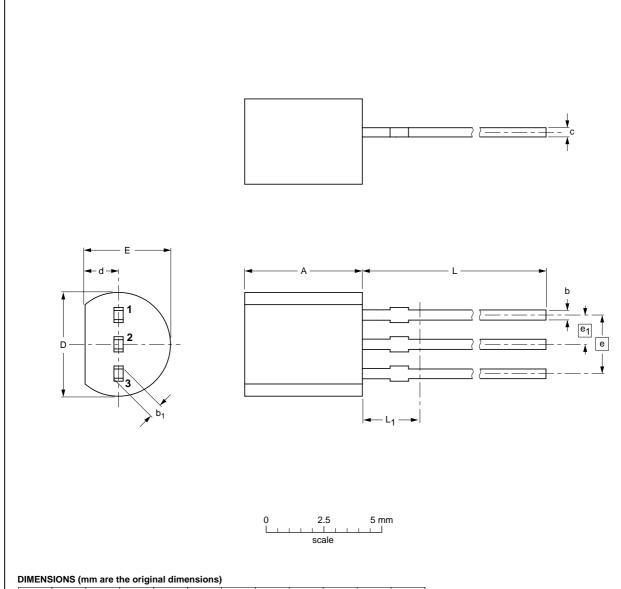
0.9

# PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTA143E series

### Plastic single-ended leaded (through hole) package; 3 leads

SOT54



UNIT	A	b	b <sub>1</sub>	С	D	d	E	е	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup> max.	
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5	

#### Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

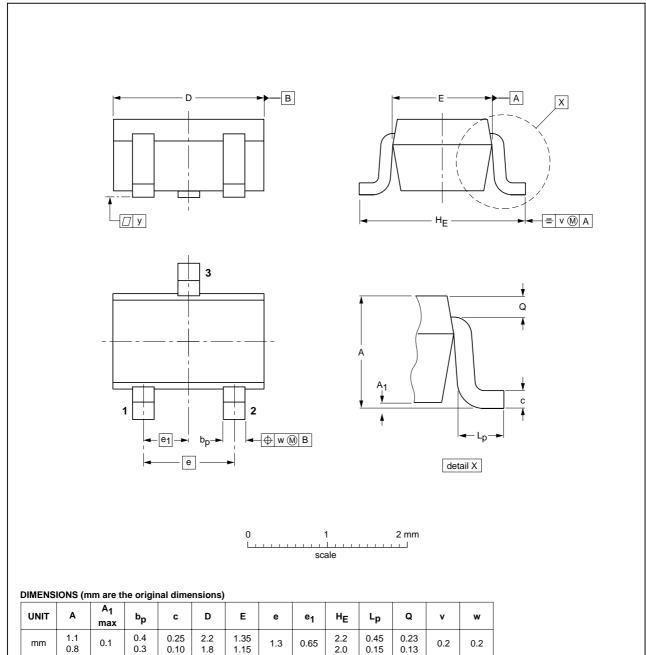
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC JEDEC JEITA			PROJECTION	ISSUE DATE	
SOT54		TO-92	SC-43A			<del>-04-06-28</del> 04-11-16

# PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTA143E series

### Plastic surface-mounted package; 3 leads

**SOT323** 



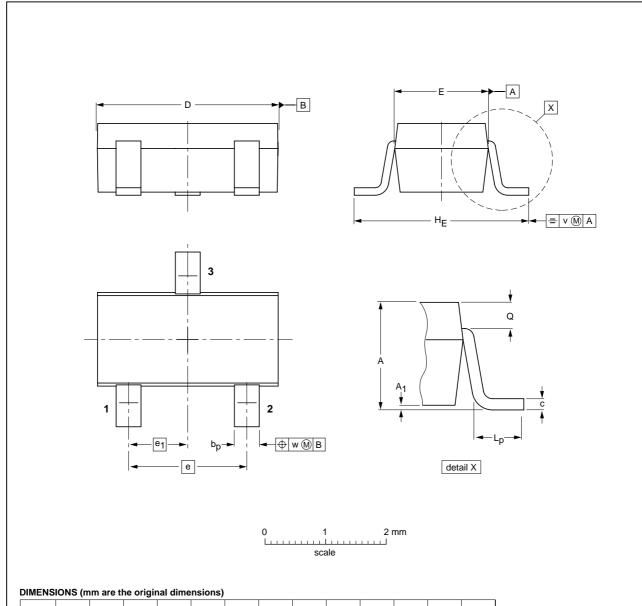
VERSION IEC JEDEC JEITA PROJECTION  SOT323  SC-70  Od-11-04	OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
SO1323   SC-70   +	VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
— \$\psi_{00-03-10}\$	SOT323			SC-70		<del>04-11-04</del> 06-03-16

# PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTA143E series

## Plastic surface-mounted package; 3 leads

SOT346



UNIT	Α	A <sub>1</sub>	bp	С	D	E	е	e <sub>1</sub>	HE	Lp	Q	v	w
mm	1.3 1.0	0.1 0.013	0.50 0.35	0.26 0.10	3.1 2.7	1.7 1.3	1.9	0.95	3.0 2.5	0.6 0.2	0.33 0.23	0.2	0.2

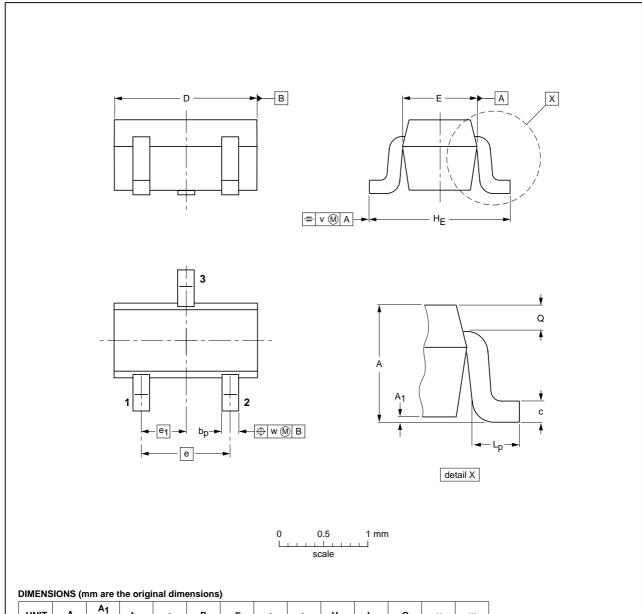
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE	
SOT346		TO-236	SC-59A		<del>-04-11-11</del> 06-03-16	

# PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTA143E series

### Plastic surface-mounted package; 3 leads

**SOT416** 



UNIT	Α	A <sub>1</sub> max	bp	С	D	E	е	e <sub>1</sub>	HE	Lp	ø	v	w
mm	0.95 0.60	0.1	0.30 0.15	0.25 0.10	1.8 1.4	0.9 0.7	1	0.5	1.75 1.45	0.45 0.15	0.23 0.13	0.2	0.2

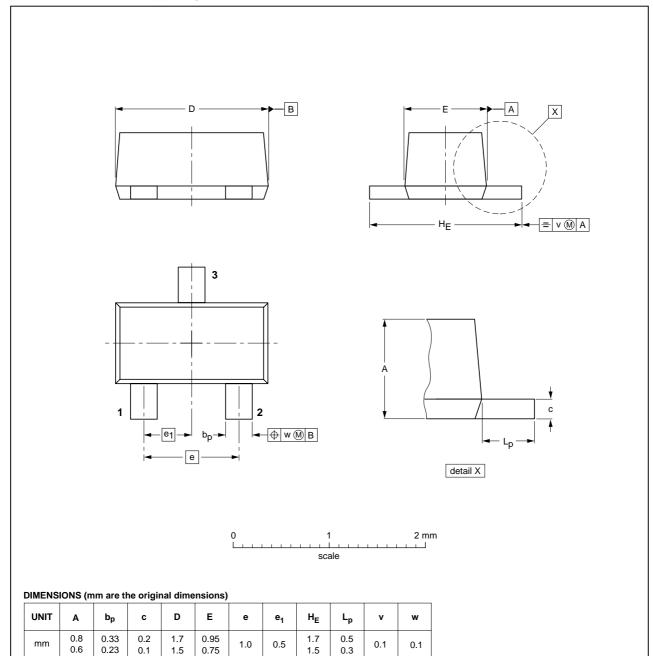
OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE	
SOT416			SC-75		<del>04-11-04</del> 06-03-16	

# PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTA143E series

### Plastic surface-mounted package; 3 leads

SOT490



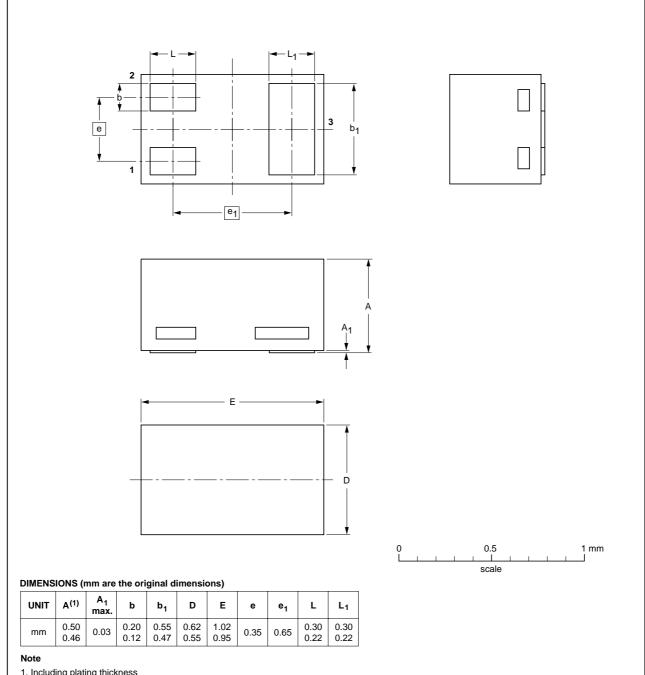
VERSION IEC JEDEC JEITA PROJECTION 95-07	OUTLINE		REFER	ENCES	 EUROPEAN	ISSUE DATE	
	VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE	
30-09 06-03	SOT490			SC-89		<del>05-07-28</del> 06-03-16	

# PNP resistor-equipped transistors; $R1 = 4.7 \text{ k}\Omega$ , $R2 = 4.7 \text{ k}\Omega$

## PDTA143E series

### Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

**SOT883** 



1. Including plating thickness

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT883			SC-101		<del>03-02-05</del> 03-04-03

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## PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

### PDTA143E series

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

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